

# 74LVC27

## Triple 3-input NOR gate

Rev. 6 — 27 October 2011

Product data sheet

### 1. General description

The 74LVC27 provides three 3-input NOR functions.

### 2. Features and benefits

- Wide supply voltage range from 1.2 V to 3.6 V
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
  - ◆ JESD8-7A (1.65 V to 1.95 V)
  - ◆ JESD8-5A (2.3 V to 2.7 V)
  - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-B exceeds 200 V
  - ◆ CDM JESD22-C101E exceeds 1000 V
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC27D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74LVC27DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74LVC27PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74LVC27BQ	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85\text{ mm}$	SOT762-1



### 4. Functional diagram

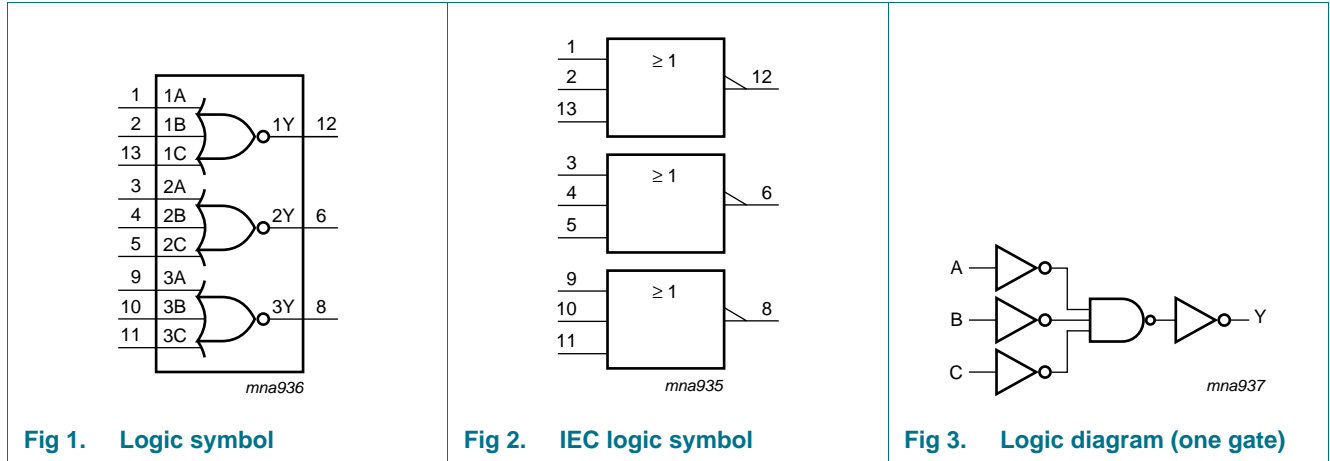


Fig 1. Logic symbol

Fig 2. IEC logic symbol

Fig 3. Logic diagram (one gate)

### 5. Pinning information

#### 5.1 Pinning

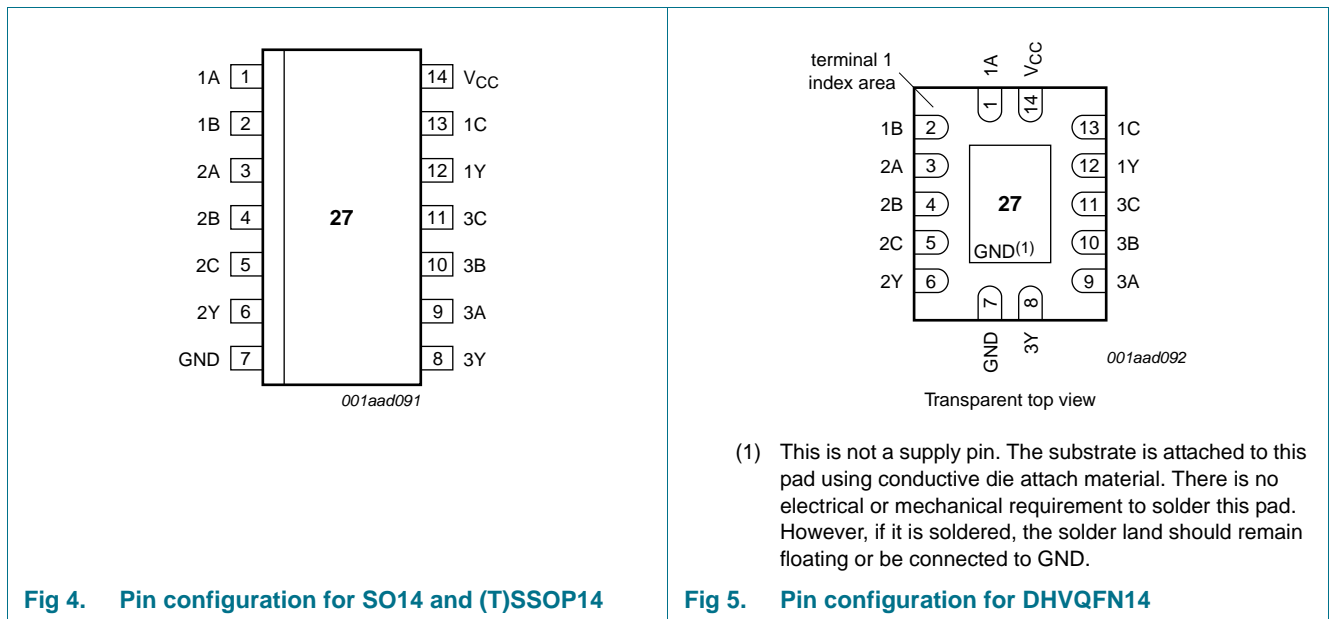


Fig 4. Pin configuration for SO14 and (T)SSOP14

Fig 5. Pin configuration for DHVQFN14

- (1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

## 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A	1, 3, 9	data input
1B, 2B, 3B	2, 4, 10	data input
1C, 2C, 3C	13, 5, 11	data input
1Y, 2Y, 3Y	12, 6, 8	data output
GND	7	ground (0 V)
V <sub>CC</sub>	14	supply voltage

## 6. Functional description

Table 3. Function selection<sup>[1]</sup>

Input			Output
nA	nB	nC	nY
L	L	L	H
X	X	H	L
X	H	X	L
H	X	X	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+6.5	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0	-50	-	mA
V <sub>I</sub>	input voltage		<sup>[1]</sup> -0.5	+5.5	V
I <sub>OK</sub>	output clamping current	V <sub>O</sub> > V <sub>CC</sub> or V <sub>O</sub> < 0	-	±50	mA
V <sub>O</sub>	output voltage		<sup>[2]</sup> -0.5	V <sub>CC</sub> + 0.5	V
I <sub>O</sub>	output current	V <sub>O</sub> = 0 V to V <sub>CC</sub>	-	±50	mA
I <sub>CC</sub>	supply current		-	100	mA
I <sub>GND</sub>	ground current		-100	-	mA
T <sub>stg</sub>	storage temperature		-60	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +85 °C	<sup>[3]</sup> -	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO14 packages: above 70 °C the value of P<sub>tot</sub> derates linearly with 8 mW/K.  
 For (T)SSOP14 packages: above 60 °C the value of P<sub>tot</sub> derates linearly with 5.5 mW/K.  
 For DHVQFN14 packages: above 60 °C the value of P<sub>tot</sub> derates linearly with 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature	in free air	-40	-	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65\text{ V to }2.7\text{ V}$	0	-	20	ns/V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	0	-	10	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 1.2\text{ V}$	1.08	-	-	1.08	-	V
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	-	-	1.7	-	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2.0	-	-	2.0	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 1.2\text{ V}$	-	-	0.12	-	0.12	V
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	-	-	$0.35 \times V_{CC}$	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-	-	0.7	-	0.7	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	-	-	0.8	-	0.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}\text{ or }V_{IL}$						
		$I_O = -100\ \mu\text{A}; V_{CC} = 1.65\text{ V to }3.6\text{ V}$	$V_{CC} - 0.2$	-	-	$V_{CC} - 0.3$	-	V
		$I_O = -4\text{ mA}; V_{CC} = 1.65\text{ V}$	1.2	-	-	1.05	-	V
		$I_O = -8\text{ mA}; V_{CC} = 2.3\text{ V}$	1.8	-	-	1.65	-	V
		$I_O = -12\text{ mA}; V_{CC} = 2.7\text{ V}$	2.2	-	-	2.05	-	V
		$I_O = -18\text{ mA}; V_{CC} = 3.0\text{ V}$	2.4	-	-	2.25	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}\text{ or }V_{IL}$						
		$I_O = 100\ \mu\text{A}; V_{CC} = 1.65\text{ V to }3.6\text{ V}$	-	-	0.2	-	0.3	V
		$I_O = 4\text{ mA}; V_{CC} = 1.65\text{ V}$	-	-	0.45	-	0.65	V
		$I_O = 8\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.6	-	0.8	V
		$I_O = 12\text{ mA}; V_{CC} = 2.7\text{ V}$	-	-	0.4	-	0.6	V
		$I_O = 24\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.55	-	0.8	V
$I_I$	input leakage current	$V_{CC} = 3.6\text{ V}; V_I = 5.5\text{ V or GND}$	-	$\pm 0.1$	$\pm 5$	-	$\pm 20$	$\mu\text{A}$

**Table 6. Static characteristics ...continued**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A	-	0.1	10	-	40	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>CC</sub> = 2.7 V to 3.6 V; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; I <sub>O</sub> = 0 A	-	5	500	-	5000	μA
C <sub>I</sub>	input capacitance	V <sub>CC</sub> = 0 V to 3.6 V; V <sub>I</sub> = GND to V <sub>CC</sub>	-	5.0	-	-	-	pF

[1] All typical values are measured at V<sub>CC</sub> = 3.3 V (unless stated otherwise) and T<sub>amb</sub> = 25 °C.

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>pd</sub>	propagation delay	nA, nB, nC to nY; see <a href="#">Figure 6</a> <sup>[2]</sup>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.5	4.6	11.6	0.5	13.4	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	2.7	6.6	1.0	7.6	ns
		V <sub>CC</sub> = 2.7 V	1.1	2.8	7.0	1.1	8.1	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.8	2.4	5.9	0.8	6.8	ns
C <sub>PD</sub>	power dissipation capacitance	per gate; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[3]</sup>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	3.3	-	-	-	pF
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	6.4	-	-	-	pF
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	9.2	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and V<sub>CC</sub> = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.[3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).P<sub>D</sub> = C<sub>PD</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>i</sub> × N + Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) where:f<sub>i</sub> = input frequency in MHz; f<sub>o</sub> = output frequency in MHzC<sub>L</sub> = output load capacitance in pFV<sub>CC</sub> = supply voltage in Volts

N = number of inputs switching

Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs

11. AC waveforms

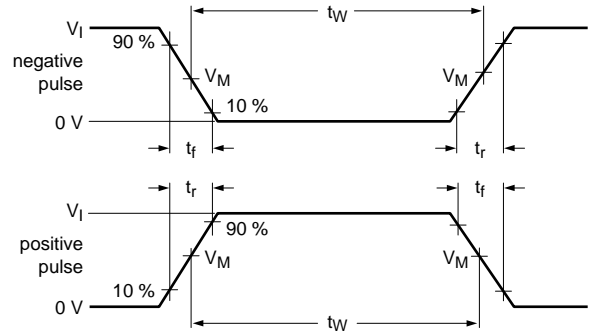
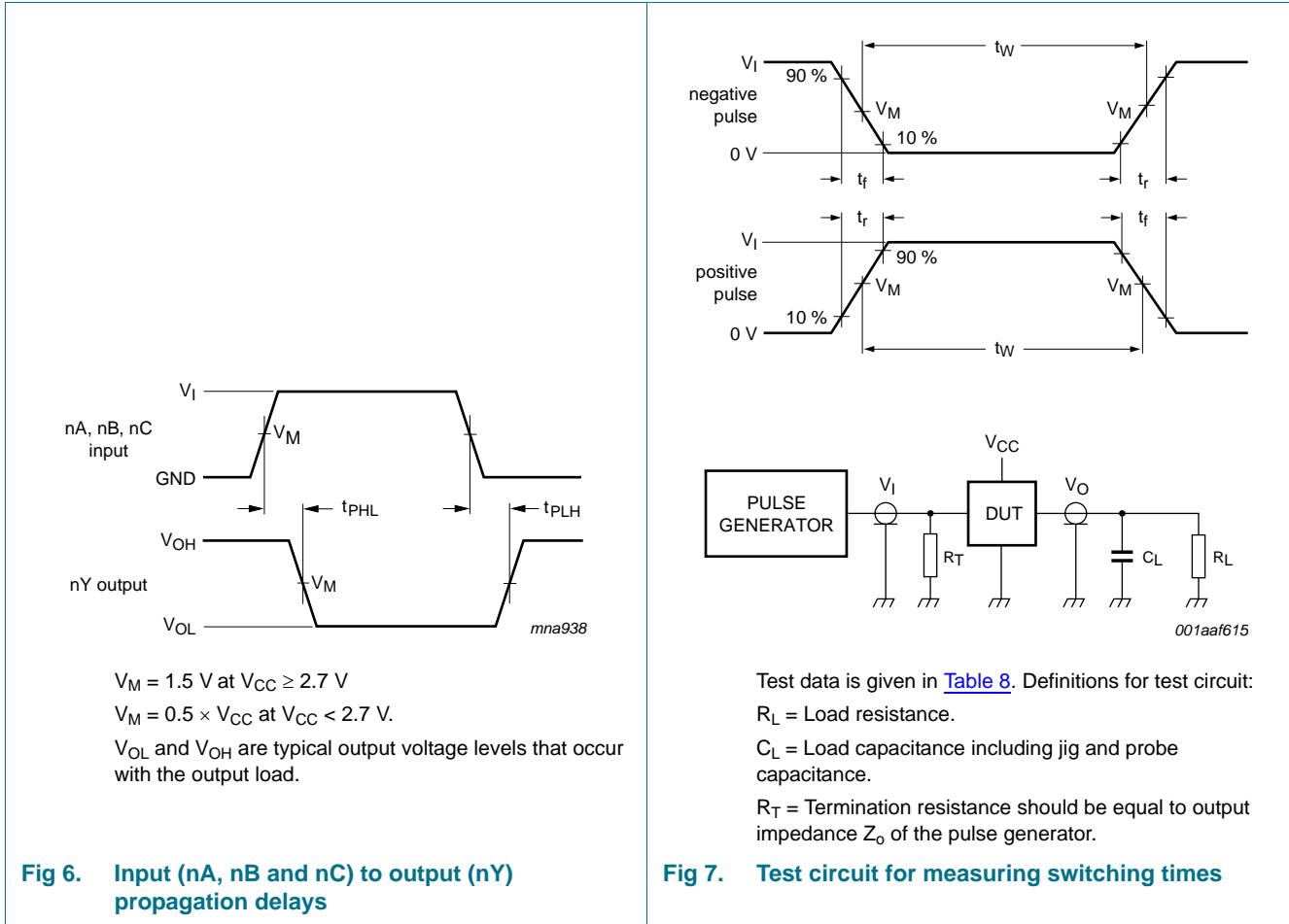


Table 8. Test data

Supply voltage	Input		Load	
	$V_I$	$t_r, t_f$	$C_L$	$R_L$
1.2 V	$V_{CC}$	$\leq 2 \text{ ns}$	30 pF	1 k $\Omega$
1.65 V to 1.95 V	$V_{CC}$	$\leq 2 \text{ ns}$	30 pF	1 k $\Omega$
2.3 V to 2.7 V	$V_{CC}$	$\leq 2 \text{ ns}$	30 pF	500 $\Omega$
2.7 V	2.7 V	$\leq 2.5 \text{ ns}$	50 pF	500 $\Omega$
3.0 V to 3.6 V	2.7 V	$\leq 2.5 \text{ ns}$	50 pF	500 $\Omega$

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

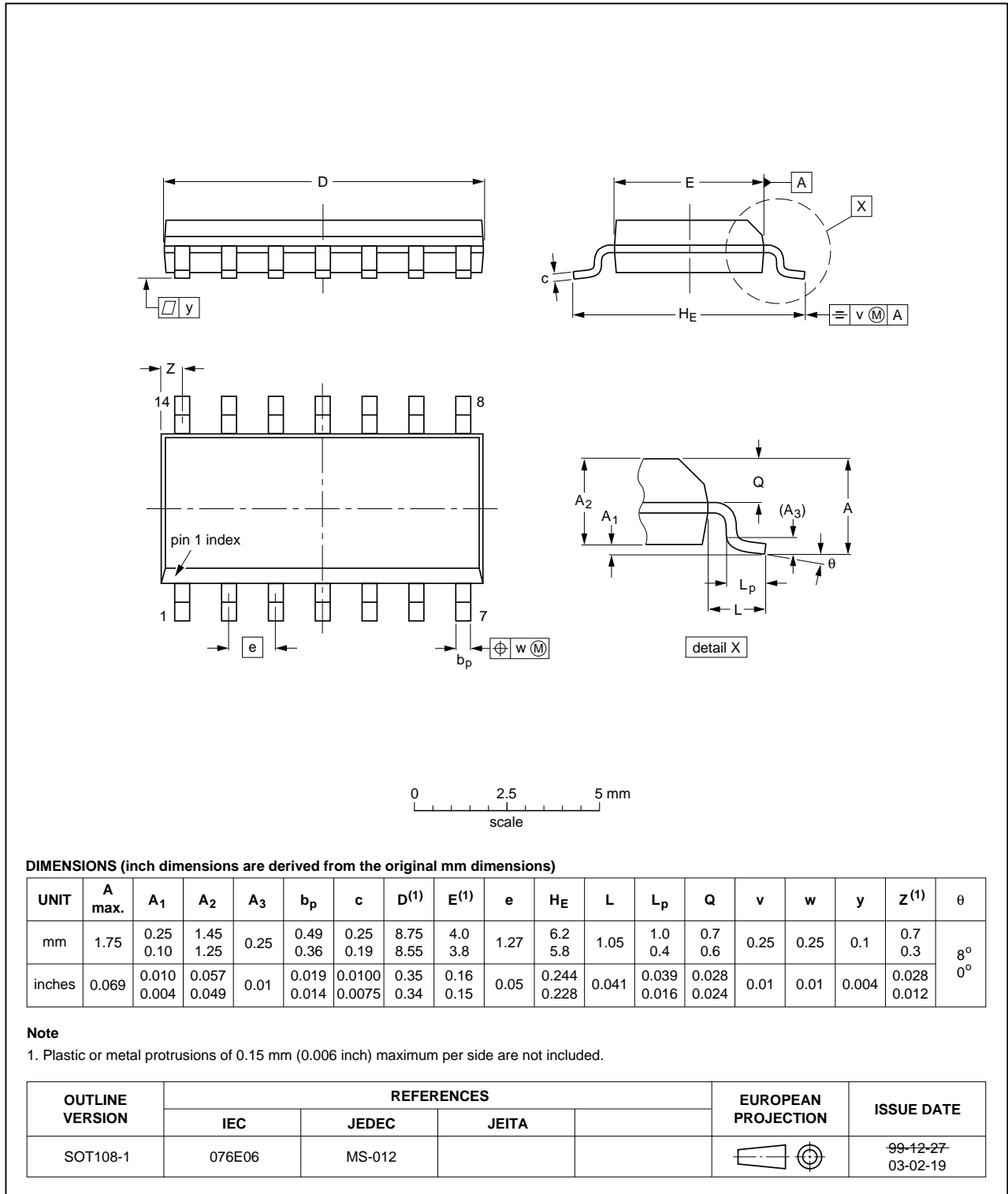


Fig 8. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

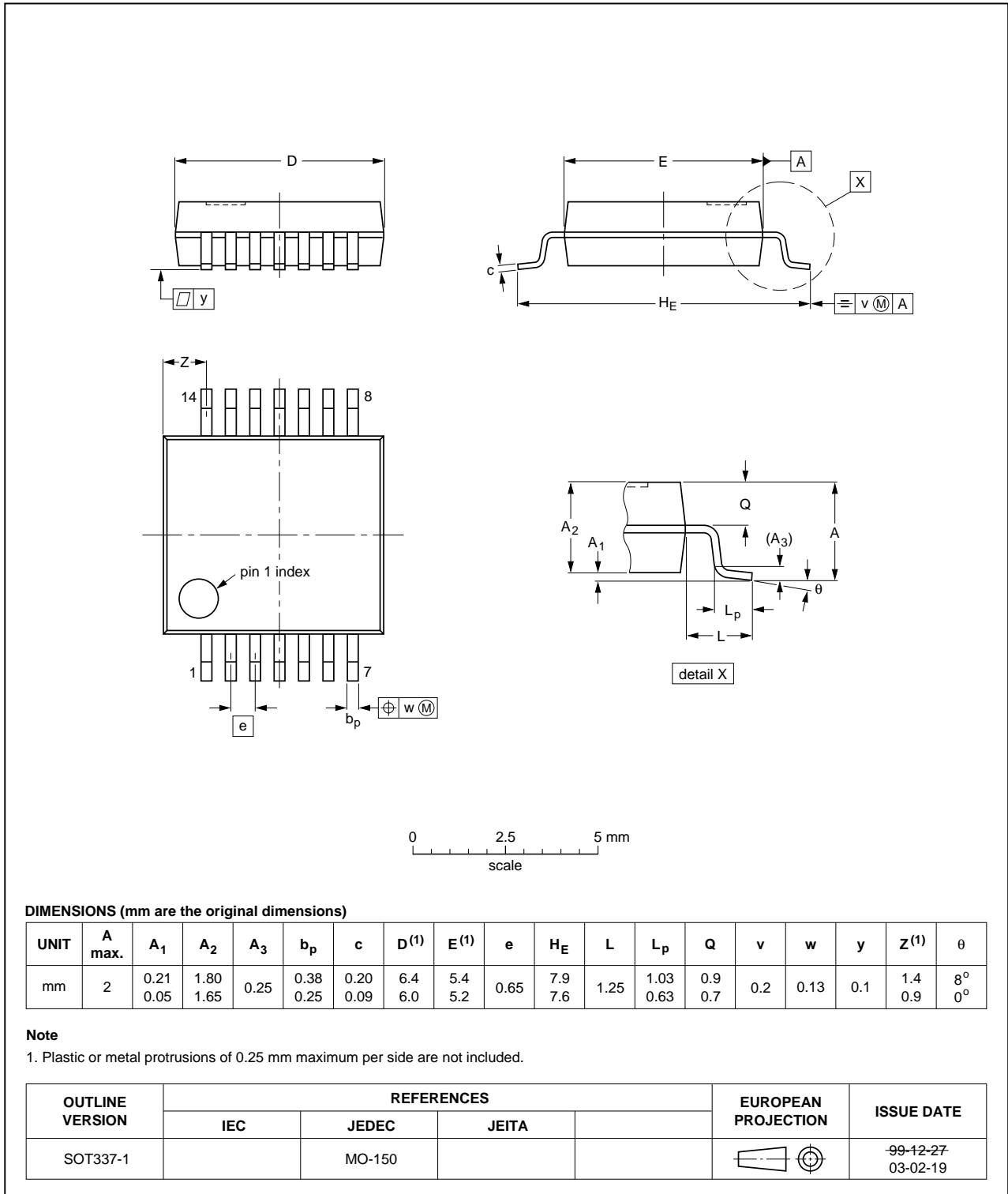


Fig 9. Package outline SOT337-1 (SSOP14)



TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

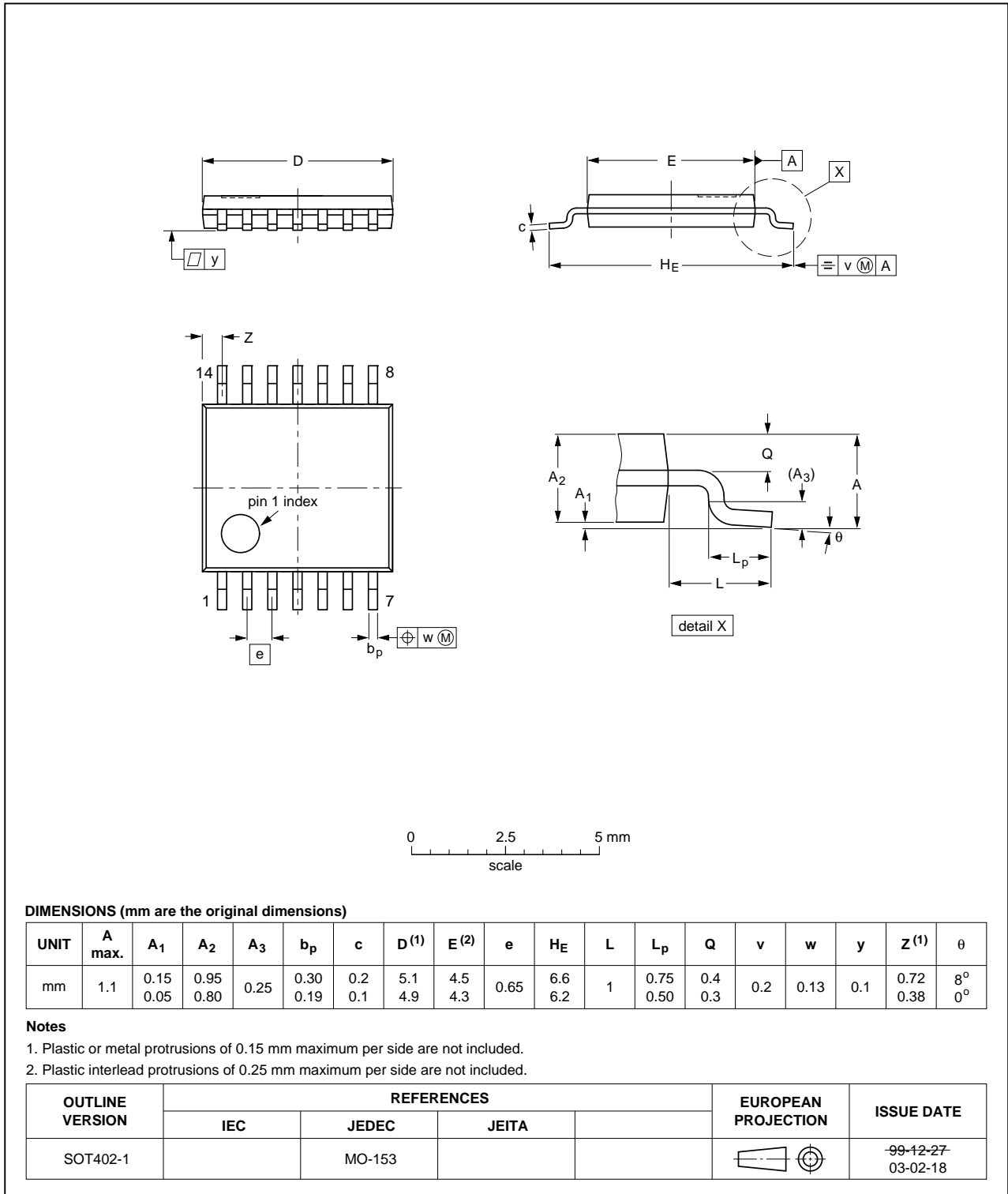


Fig 10. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

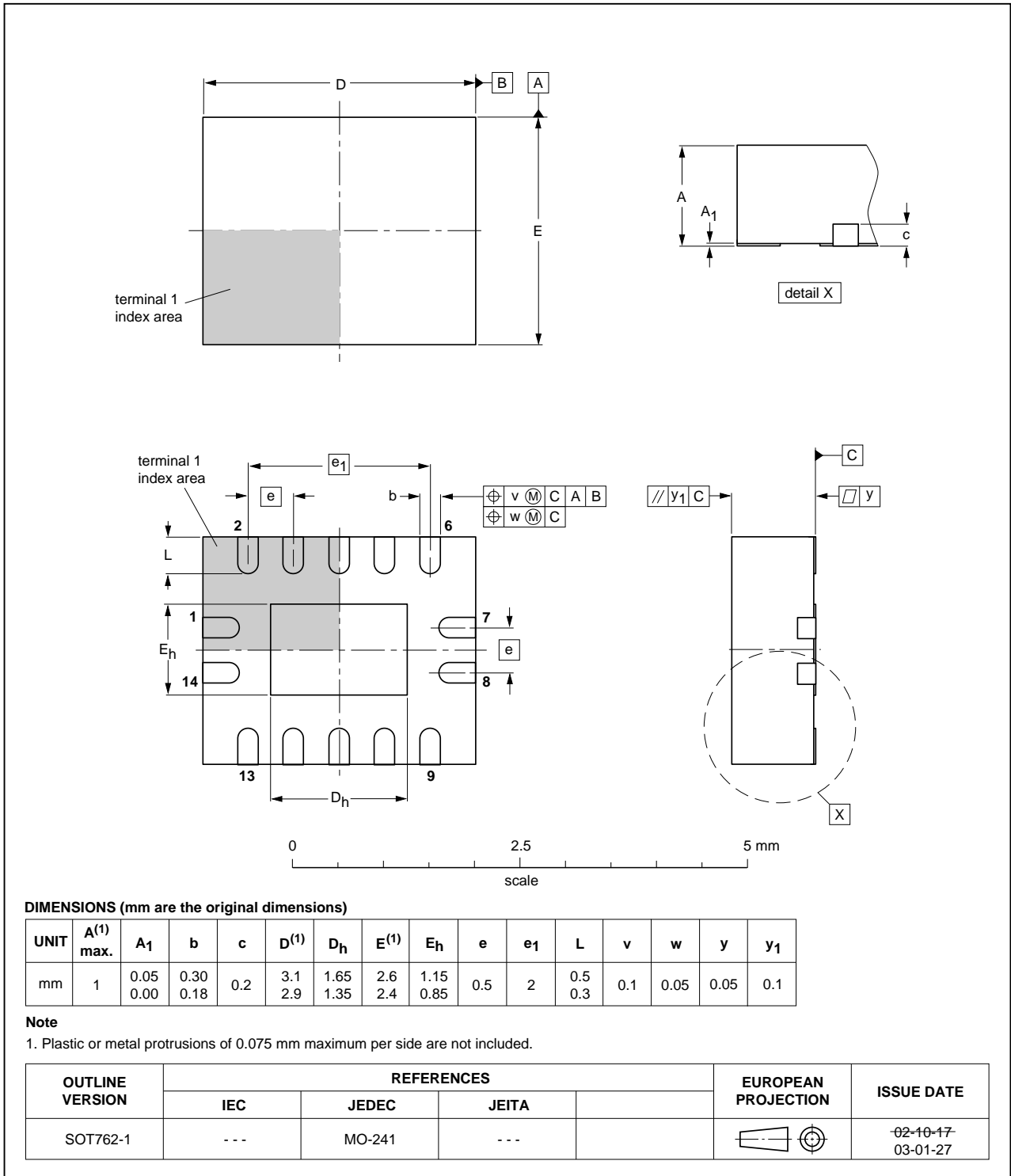


Fig 11. Package outline SOT762-1 (DHVQFN14)

## 13. Abbreviations

**Table 9. Abbreviations**

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

**Table 10. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC27 v.6	20111027	Product data sheet	-	74LVC27 v.5
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Table 7</a> : values added for lower voltage ranges.</li> </ul>			
74LVC27 v.5	20110909	Product data sheet	-	74LVC27 v.4
Modifications:	<ul style="list-style-type: none"> <li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>• Legal texts have been adapted to the new company name where appropriate.</li> <li>• <a href="#">Table 4</a>, <a href="#">Table 5</a>, <a href="#">Table 6</a>, <a href="#">Table 7</a> and <a href="#">Table 8</a>: values added for lower voltage ranges.</li> </ul>			
74LVC27 v.4	20040113	Product specification	-	74LVC27 v.3
74LVC27 v.3	19980428	Product specification	-	74LVC27 v.2
74LVC27 v.2	19980406	Product specification	-	74LVC27 v.1
74LVC27 v.1	-	-	-	-

## 15. Legal information

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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